



PART NO. : TG10-DA1NSLF

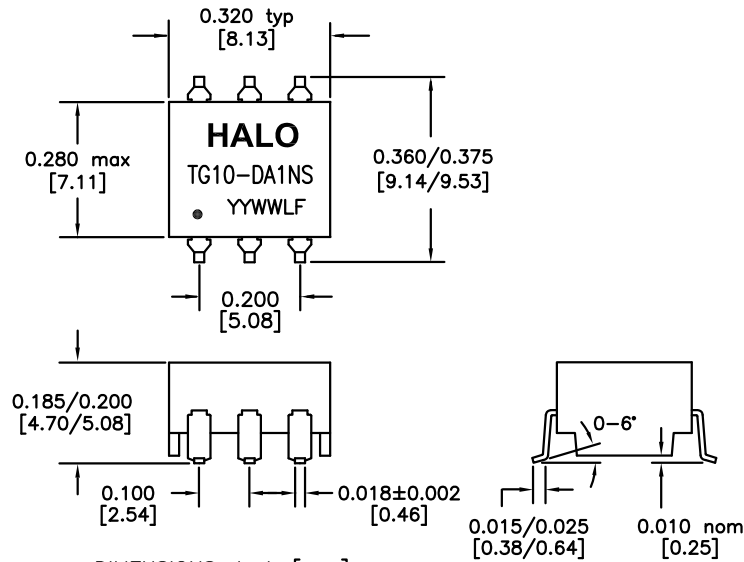
6PIN SMT ISOLATION MODULE
 DESIGNED FOR CIRRUS LOGIC DIGITAL AUDIO
 INTERFACE APPLICATIONS

LEAD-FREE/RoHS COMPLIANT

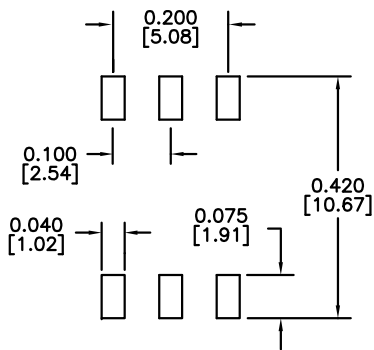
COMPATIBLE TO LEAD-FREE SOLDERING PROCESS
 CONDITION PER IPC/JEDEC J-STD-020C

UL/EN60950 AND DEMKO RECOGNIZED

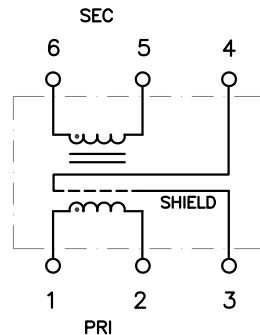
EXTENDED OPERATING TEMPERATURE -40/+85°C



DIMENSIONS: Inch [mm]
 CO-PLANARITY: 0.004 [0.10]
 TOLERANCES: ±0.005 INCH IF NOT SPECIFIED



RECOMMENDED SOLDER PAD DIMENSIONS



ONLY ONE END OF THE SHIELD CAN BE GROUNDED

ELECTRICAL SPECIFICATIONS @25°C

TURNS RATIO P1-2:P6-5 OCL (100kHz,0.1V) P1-2 DCR P1-2 LL P1-2 Cw/w P1-6 (Ground P3) BANDWIDTH (Nominal) ISOLATION PRI - SEC PRI,SEC - SHIELD	1:1 ±2% 750µH nom 0.5Ω max 1.0µH max 18pF max 9pF max 10kHz-200MHz 1500Vrms 1500Vrms
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HALO/PBL

CALIFORNIA, USA
 KOWLOON, HONG KONG
 SINGAPORE

TITLE	ISOLATION MODULE		SIGNATURES	DATE	REV.	DESC.	DATE
FOR	CIRRUS LOGIC DIGITAL AUDIO		DRAWN	LI ZHI ZHONG	5/4/16	A	PROD. RELEASE
PART NO.	TG10-DA1NSLF		CHECKED	LEI KEONG	8/8/16	B	ADD BW SPEC.
SCALE	NONE	PAGE	1 OF 1	APPROVED	PETER LU	8/8/16	C
				FILE	DA1NSLF.DWG	D	UPDATE DESC.
							8/8/16